

What is claimed is:

1. A heat sink having an assembly device adapting
to a hole formed on a motherboard and being assembled
over a chip for dissipating energy generated by said
chip to ^{the} exterior, said heat sink comprises: ^{ing}

a chassis having a configuration and dimension
substantially identical with the shape of said chip, a
plurality of fins formed thereon constructing a heat
dissipating surface, and a planar chassis edge defined
by a planar surface between an outer most edge thereof
and said heat dissipating surface, said chassis further
having a plurality of fastening ends extending from
said chassis edge, each of which fastening ends ^{is} ~~being~~
formed with a fastening hole having a first diameter;

a plurality of fastening bolts ^{in the} ~~of a~~ same quantity
as said fastening holes, each fastening ^{bolt} ~~hole~~ being
substantially in a columnar configuration and having a
head portion, a bolt body, and an insertion end from
the top down, wherein said fastening bolt can penetrate
through said fastening holes of said fastening ends,
said bolt body is telescopically provided with a
helical spring, and said insertion end is adapted to be
clamped into said holes formed on said motherboard
subjecting said helical spring ^{to compression} ~~urging~~ against said
fastening ends;

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whereby said heat sink is resiliently pressed against said chip by means of urging said fastening seat and said helical spring against said chassis as well as clamping said fastening bolts into said holes
5 formed on said motherboard.

2. A heat sink having an assembly device according to claim 1, wherein said fastening bolts are each formed with a narrow opening penetrating from a furthestmost end of said insertion end and extends into
10 a portion of said bolt body.

3. A heat sink having an assembly device adapting to a hole formed on a motherboard and being assembled over a chip for dissipating energy generated by said chip to exterior, said heat sink comprises,
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a chassis having a configuration and dimension substantially identical with the shape of said chip, a plurality of fins formed thereon constructing a heat dissipating surface, and a planar chassis edge defined by a planar surface between an outer most edge thereof
20 and said heat dissipating surface;

a fastening seat formed by a resiliently curvable and integrally formed hollow sheet, said fastening seat comprising:

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an outer rim being so shaped and dimensioned as to
be consistent with those of said chassis edge and to
allow said outer rim ^{to be} being telescopically provided over
said chassis edge, said outer rim being distinguished
5 into a first section, a second section, a third
section, and a forth section which are sequentially
connected, wherein the shape and dimension of said
first and third sections are consistent with and
disposed symmetrically about each other; and those of
10 said second and forth sections are consistent with and
disposed symmetrically about each other, said first and
third sections extend horizontally, and said second and
forth sections incline upwardly and outwardly;

wherein an L-shaped and downward-suspended hook
15 extends outwardly from center of each said second and
forth sections, the shape and dimension of said hooks
are consistent with and disposed symmetrically about
each other, and said downward-suspended ends of said
hooks each comprise a V-shaped barb, an apex of said V-
20 shaped barb converges toward said chip, a lower surface
of said V-shaped barb defines a contact surface adapted
to be clamped into said holes formed on said
motherboard whereby said first and third sections are
pressed against said chassis edge by means of
25 resilience of said second and forth sections.

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